

AMENDMENTS TO THE ABSTRACT

Please replace the paragraph at page 39 with the following rewritten paragraph:

-- ~~The invention provides a~~ A dicing and die bonding pressure-sensitive adhesive sheet having a pressure-sensitive adhesive layer that exhibits excellent embedding properties in die bonding ~~and to thereby can prevent~~ formation of voids between die pads and the pressure-sensitive adhesive layer even when chips are mounted on ~~the die pads having exhibiting great difference of~~ differences in height. The dicing and die bonding pressure-sensitive adhesive sheet comprises a base material and a pressure-sensitive adhesive layer disposed thereon, the pressure-sensitive adhesive layer having a ratio (M_{100}/M_{70}) of a modulus of elasticity at 100°C (M_{100}) to a modulus of elasticity at 70°C (M_{70}) ~~being of~~ 0.5 or less. --